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MPC5748G Low Cost EVB User Guide (MPC5748G-LCEVB)



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1. Introduction

This user guide details the setup and configuration of the NXP MPC5748G Low Cost Evaluation Board (hereafter referred to as the LCEVB). The LCEVB is intended to provide a mechanism for easy evaluation of the MPC5748G family of microcontrollers, and to facilitate basic hardware and software development.

Note that the LCEVB has a limited feature set compared to the main MPC574xG customer EVB and is intended for evaluation purposes. Customers moving to serious development activities are recommended to purchase the fully functional customer EVB which also has device specific daughter cards.

The LCEVB is intended for bench / laboratory use and has been designed using normal temperature specified components ($+70^{\circ}$ C).

This product contains components that may be damaged by electrostatic discharge. Observe precautions for handling electrostatic sensitive devices when using the LCEVB.

The user guide is intended to be read alongside the respective MCU documentation available at www.nxp.com and includes:

- Reference Manuals
- Product Data Sheets
- Application notes
- Device Errata

2. LCEVB Features

The LCEVB provides the following key features:

- Single 5 V DC external power supply input with on-board 3.3 V regulator. Power is supplied via a 2.1 mm barrel style power jack.
- Simple jumper less configuration (enhanced configuration is possible via 0 Ohm Resistors and optional jumpers if required).
- Master power switch and regulator status LED.
- USB Serial interface.
- 2 x High Speed CAN transceiver routed to 3-way headers.
- 2 x LIN interfaces routed to 3-way headers.
- Main clock supplied from on board crystal.
- User reset switch with reset status LED's.
- Ethernet PHY and RJ45 socket (configured for MII mode).
- USB Type A Host interface.
- 2 x FlexRay interfaces with standard 2-pin connectors.
- 14-pin JTAG connector.

- 4 user LED's wired to MCU ports.
- 2 user pushbutton switches wired to MCU ports.
- Hexadecimal encoded switch wired to 4 MCU ports.
- Simple potentiometer connected to analogue input channel.

2.1. Differences to the Customer EVB

Note that the GPIO pins used for peripherals on the LCEVB are the same as those used on the customer EVB. This ensures maximum code compatibility between the 2 boards, making it easy to migrate from one board to the other

Table 1. Customer EVB vs LCEVB features

Feature	Customer EVB	LCEVB
MCU Support	Custom MCU Daughter cards for multiple devices (socketed)	Soldered 176QFP MPC5748G
Power Supply	External 12 V	External 5 V (Caution)
On Board Regulators (and LED's)	5 V, 3.3 V, 1.25 V (combination of Linear and /or Switching regulators)	3.3 V Switching Regulator
Master Power Switch	Yes	Yes
Reset Control	Reset button with MCU and External Reset LED's	Reset button with MCU and External Reset LED's
USB FTDI Serial Interface	Yes	Yes
CAN Physical Interfaces	2 (routed to 0.1" headers)	2 (routed to 0.1" headers)
LIN Physical Interfaces	2 (routed to Molex headers)	2 (routed to 0.1" headers)
FlexRay Physical Interfaces	2 (routed to 0.1" headers)	2 (routed to 0.1" headers)
Ethernet Physical Interface	1 (MII and RMII Support)	1 (MII only mode)
USB Physical Interface	2 (USB Host and OTG)	1 (USB Host)
MLB Daughter card Connector	Yes	No
SAI Audio / TWRPI Connectors	Yes	No
SDHC Connector	Full Size SDHC Socket	No
Fast External Osc (FXOSC)	Daughter card Crystal * and SMA input connector	40 MHz Crystal
Slow External Osc (SXOSC)	Daughter card Crystal *	32.768 KHz Crystal
CLKOUT signals available	Yes (GPIO Matrix)	Yes (Standalone pads)
User LEDS	4	4
User Pushbutton Switches	4	2
Hex Encoded Switch	Yes	Yes
Test Potentiometer for ADC	Yes	Yes
GPIO Matrix	All Available Pins not otherwise used for peripherals	Selection of Pins available from 5 GPIO Ports
Debug	14 Pin JTAG and 50 pin Nexus	14 Pin JTAG
Configuration	Highly configurable via jumper shunts	Fixed (limited configuration via 0 ohm resistors)

^{*} Daughter card crystals are typically 40 MHz for FXOSC and 32.768 KHz for SXOSC but may vary between daughter cards.

The figure below shows the customer EVB (left) next to the LCEVB (right).

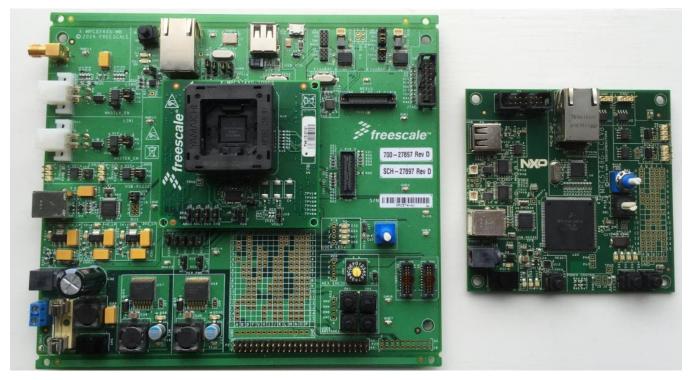


Figure 1. Customer and LCEVB side by side

3. Configuration Overview

Out of the box, there is no configuration required for the LCEVB to function. Unlike the customer EVB, the LCEVB is primarily designed for a single mode of operation with no requirement for user configuration. If you wish to have a more flexible configuration the recommendation is that the fully configurable customer EVB is purchased.

There are however some jumper footprints and zero ohm resistors populated in positions that would normally have jumper headers fitted (for example on the MCU power supply lines and tracking to the peripheral interfaces). If required these can be de-soldered to modify functionality. Any such modification is done at the full risk of the user and no support or warranty repairs will be provided for a board that has been modified. Modifications should only be attempted by appropriately trained personnel using the correct equipment and Personal Protective Apparel

The diagram below gives an overview of the functional blocks of the LCEVB

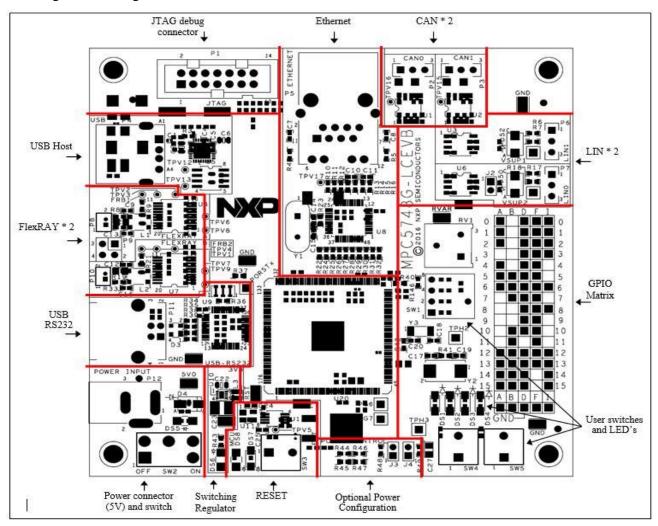
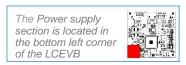


Figure 2. EVB Functional Blocks

4. Initial Setup

This section details the power, reset, clocks, and debug configuration which is the minimum configuration needed in order to power ON the LCEVB.

4.1. Power Supply Configuration



The LCEVB requires an external power supply voltage of 5 V DC, minimum 1 A. There is a single 3.3 V switching regulator on the LCEVB providing MCU and peripheral power.

CAUTION

Connecting a power supply with a voltage greater than 5 V will result in irrecoverable board damage. Check the power supply voltage before connecting the plug to the LCEVB.

4.1.1. Power Input Connector

Power is supplied to the LCEVB via a 2.1 mm connector from the wall-plug mains adapter as shown below. Note – if a replacement or alternative adapter is used, care must be taken to ensure the 2.1 mm plug uses the correct polarization as shown below:

V+(5V)

Figure 3. 2.1 mm Power Connector

4.1.2. Power Switch

Slide switch SW2 can be used to isolate the power supply input from the EVB voltage regulators if required.

- Moving the slide switch to the right (away from the power connector) will turn the EVB ON.
- Moving the slide switch to the left (towards the power connector) will turn the EVB OFF.

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4.1.3. Power Status LED

When power is applied to the LCEVB, two green LED's adjacent to the regulator and power connector show the presence of the supply voltages as follows:

- LED DS5 Indicates that the 5.0 V supply voltage is present
- LED DS6 Indicates that the 3.3 V switching regulator is functioning

If no LED's are illuminated when power is supplied to the LCEVB and the power switch is in the "ON" position, the power adapter may be faulty or there may be a fault with the LCEVB. If only one LED is illuminated there may be a short in that power supply rail – check there is nothing shorting on the EVB. If you continue to have problems, contact NXP for support.

CAUTION

In the event of a short on the regulator output (in which case one of the LED's would be off or dimly illuminated), the regulator and/or the shorted component will likely be hot.

4.1.4. MCU and Peripheral Voltage Configuration

The following MCU supply rails are connected to the 3.3 V switching regulator:

- VDD_HV_ADC0
- VDD_HV_ADC1
- VDD_HV_ADC1_REF
- VDD HV A
- VDD_HV_B
- VDD_HV_FLA
- External Ballast Transistor Supply

Similarly all of the peripheral interfaces (or the I/O power in the peripheral interface) are supplied from 3.3 V as is the reset circuitry and the voltage sense wire on the JTAG connector.

4.2. Reset Control (SW3)



The MCU has a single bi-directional open drain Reset pin. Rather than connect multiple devices to the reset pin directly, a reset-in and reset-out buffering scheme has been implemented on the LCEVB as shown in Figure 4. The reset "in" from the reset switch (SW3) and the debug connectors are logically OR'd together using an AND gate and then connected to the buffer to provide an open-drain output.

The "reset-out" circuitry provides a buffered reset signal that can be used to drive any circuitry requiring a reset control from the MCU.

This scheme is not required if it is guaranteed that anything driving the reset pin has an open drain drive and that there is no significant output load on the MCU reset pin.

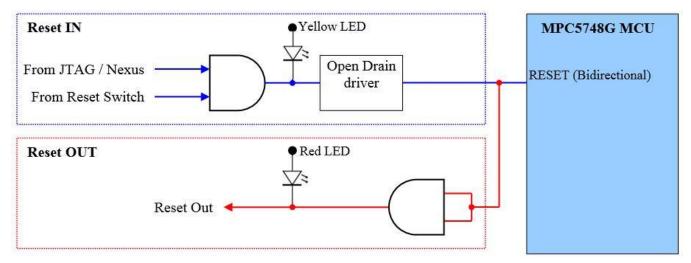


Figure 4. EVB Reset Control

4.2.1. Reset LEDs

As can be seen above, there are two reset LED's that can be used to identify the source / cause of a reset: RED LED DS8 (titled "MCU") will illuminate if:

- The MCU issues a reset (in this condition ONLY this LED will be illuminated and LED DS1 will be off)
- There is a target reset (i.e. from the reset switch or from the debugger in which case LED DS1 will be ON)

YELLOW LED DS7 (titled "EXT") will illuminate when an external hardware device issues a reset to the MCU:

- The reset switch is pressed
- There is a reset being driven from one of the debug connectors

		<u> </u>
LED DS7 (Yellow) LED DS8 (Red)		Description
OFF OFF No Reset being issued from MCU or external logic		No Reset being issued from MCU or external logic
OFF ON MCU has		MCU has issued a reset
ON	OFF	External reset issued from switch or debug BUT not being issued to MCU (check R137 has not been removed)
ON ON External reset issued from reset switch or debug and ha		External reset issued from reset switch or debug and has been issued to MCU

Table 2. Reset LED Decoding

MPC5748G Low Cost EVB User Guide, User Guide, Rev. 1, 08/2016

4.3. MCU Clock Configuration

There is an external 40MHz crystal connected to the MCU Fast External Oscillator (FXOSC) pins EXTAL and XTAL.

There is also a 32.768 crystal connected to the MCU Slow External Oscillator (SXOSC) pins OSC32K_EXTAL and OSC32K_XTAL. This can be used for accurate time keeping.

There are 2 pads PG6 and PG7 (located just below the MCU) on the LCEVB to facilitate measurement of the CLKOUT1 and CLKOUT0 signals.

Note – there is no external clock input on the LCEVB

4.4. Debug Connector (P1)



The LCEVB has a single 14-pin keyed JTAG connector for connection to an external debugger.

Before attaching or removing the debug cable from the LCEVB remove power from the EVB to prevent damage to the LCEVB or debug hardware.

4.4.1. Debug Connector Pinout

The following tables list the pinout for the JTAG connector used on the LCEVB

Pin No **Function** Connection Pin No **Function** Connection 1 TDI PC₀ 2 **GND GND** 3 TDO PC1 4 **GND GND** 5 **TCLK** PH9 6 **GND GND** 7 **EVTI** PL8 8 N/C ---9 RESET JTAG - RSTx 10 **TMS** PH₁₀ 11 **VREF** PER_HVA 12 **GND GND** 13 **RDY** 14 **JCOMP** 10k Pulldown

Table 3. 14-Pin JTAG Debug Connector Pinout

TDI, TDO and TMS have 10K pullup resistors on the LCEVB. TCLK has a 10K pulldown (R147) to facilitate STANDBY exit without any additional code (at the sacrifice of slightly higher STANDBY current), however this can be changed to a pullup if required by removing R147 and fitting the resistor on R56.

Table 4. Ji	AG Pins Pull State (from	MPC5/48G Reference	e Manuai)
TERMINAL TYPE	POWERUP pad state	RESET pad status	DEFAULY pad status
RESET	Strong pull-down	Strong pull-down	Weak pull-up
PORST	Weak pull-down	Weak pull-up	Weak pull-up
GPIO	High impedance	High impedance	High impedance
ANALOG	High impedance	High impedance	High impedance
EOUT0, EOUT1	High impedance	High impedance	High impedance
TCK	High impedance	Weak pull-up	Weak pull-up
TMS	High impedance	Weak pull-up	Weak pull-up
TDI	High impedance	Weak pull-up	Weak pull-up
TDO	High impedance	High impedance	High impedance

Table 4. JTAG Pins Pull State (from MPC5748G Reference Manual)

5. Communications & Memory Interfaces:

This section details the communication interface and storage peripherals that are implemented on the LCEVB.

5.1. CAN Interfaces (P2, P3)



The LCEVB incorporates two identical CAN interface circuits connected to MCU CAN0 and CAN1 using MC33901 transceivers. Both transceivers are configured for high speed operation by pulling pin 8 to GND via a 4.7 kOhm resistor. There are test points to allow the Select pin to be driven high if desired. The MC33901 is pin compatible with other CAN transceivers supporting full CAN FD data rates.

For flexibility, the CAN transceiver I/O is connected to a 0.1" header (P2 for CAN0 / P3 for CAN1) rather than using non-standard DB9 connectors. The pinout of these headers is shown below.

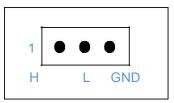


Figure 5. CAN Physical Interface Connectors

The LIN Physical interface circuits are located on the right edge of the LCEVB



5.2. LIN Interfaces (P6, P7)

The LCEVB incorporates two LIN transceiver circuits connected to MCU LIN0 and LIN1, using an NXP MC33662 transceiver. The MPC5748G LIN0 supports both master and slave modes whereas LIN1 only supports master mode.

On the LCEVB, the LIN0 transceiver is configured as slave mode by default. Master mode operation is possible by either populating a zero ohm resistor (R143) or buy fitting a jumper header (J2) – see the schematics for details. The LIN0 transceiver is hard wired for master mode. To save on board space and cost, both LIN transceivers are connected to 0.1" pitch 3x1 headers as shown below rather than the usual LIN Molex header.

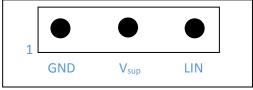


Figure 6. LIN Physical Interface Connector

Note that in order for the LIN transceiver to function, external 12v must be supplied via pin 2 of the connector

5.3. USB RS232 Serial Interface (P11)



The LCEVB incorporates a USB RS232 serial interface providing RS232 connectivity via a direct USB connection between the PC and the EVB. The circuit contains an FTDI FT2232D USB to Serial interface which should automatically install the drivers for two additional COM ports on your PC. Note that only one of these ports is used so you will need to try both (usually the higher numbered COM port is the active one). For more information on the USB drivers and general fault finding, consult the FTDI website at http://www.ftdichip.com/

The MCU LIN2 signals are routed to the FTDI transceiver (UART TX and RX). No handshaking signals are implemented and no board configuration is required.

5.4. USB HOST Interface (P4)



The LCEVB includes a Type A (Host) USB interface, routed to a USB type A female connector. The USB circuit contains a USB83340 transceiver with a MIC2026-1YM USB power switch. There is no hardware user configuration required to use the USB circuit.

The Ethernet interface is mid-way along the top edge of the LCEVB



5.5. Ethernet Interface (P5)

The EVB incorporates a single DP83848c Ethernet transceiver with the circuitry configured for MII mode. The transceiver is connected to a pulse J1011F21PNL RJ45 connector which includes a built-in isolation transformer. There is no hardware configuration needed.

If you require RMII mode or access to both Ethernet ports on the MPC5748G, please purchase the MPC5748G customer EVB and appropriate daughter cards.

Note that the MCU Ethernet signals are all in the VDD_HV_B domain. The Ethernet PHY will only function with 3.3 V I/O so if you have made any modifications to the EVB power domain configuration (via the zero ohm resistors), you need to ensure the VDD_HV_B domain is at 3.3 V before attempting to use the Ethernet module. If VDD_HV_B is set to 5 V, the signals routed to the Ethernet PHY (see the EVB schematics) must be left as tristate to prevent damage to the transceiver.

5.6. FlexRay (P8, P9, P10)

The FlexRay
interfaces are midway
down the left hand
edge of the LCEVB



The LCEVB incorporates two FlexRay TJA1080TS/N interfaces connected to MCU FlexRay channels A and B and routed to two Molex 1.25 mm pitch Pico Blade shrouded headers (standard on many NXP EVB's). There is no hardware configuration required to use FlexRay.

Note that the LCEVB is supplied with a 40 MHz crystal by default. If FlexRay is configured to use the external clock source, then the crystal should be left at 40 MHz

6. User Interface (I/O)

This section details the user I/O available on the LCEVB and includes the GPIO matrix, switches, LED's and the ADC variable resistor.

6.1. GPIO Matrix

The GPIO matrix is on the right hand edge of the LCEVB

A sub-set of available GPIO pins (available pins being those not already routed to LCEVB peripherals) are available at the GPIO matrix as detailed below. The matrix provides an easy to follow, intuitive, space saving grid of 0.1" header through-hole pads. Users can solder wires, fit headers or simply insert a scope probe into the respective pad.

To use the matrix, simply read the port letter from the top or bottom row of text then the pad number from the columns on the left or right of the matrix. For example, the 1st pad available on Port B is PB5 as outlined below.

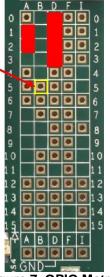


Figure 7. GPIO Matrix

If a pad is populated in the matrix, it means this is available for exclusive use as GPIO. The exception to this are the port pins detailed below which are also shared with switches or user LED's (shaded red in the matrix diagram above).

PD0, PD1, PD2, PD3 – HEX Encoder Switch PA1, PA2 – User pushbutton Switches

If you require access to all of the available GPIO pads, the customer EVB and daughter card provides this additional functionality.

The user pushbutton switches are in the bottom right corner of the LCEVB



6.2. User Switches (SW4, SW5)

There are two active high (pulled low, driven to 3.3 V) pushbutton switches on the LCEVB connected directly to MCU GPIO ports. No configuration is required to use the switches.

SW4 is connected to port PA1 (which is also the NMI pin) and SW5 is connected to port PA2

NOTE

The MCU ports used on the user pushbutton switches are also routed to the GPIO matrix.

> The hex encoder switch is located to the left of the GPIO Matrix



6.3. Hex Encoded Switch (SW1)

There is a single hex encoded 16 position rotary switch on the LCEVB. This outputs a binary encoded hex value (active high) on four MCU ports (Port D[0..3]).

HEX SW2 HEX SW4 HEX SW3 HEX SW1 **Position** (PD2) (PD3) (PD0) (PD1) A В C D Е F

Table 5. Hex Encoder Switch (SW2)

Note that POSN 0 will ensure that no voltage is applied to the pads. This allows the pads to be used as normal GPIO (with 10K pulldown) and accessed at the respective pads on the GPIO matrix area.

The user LED's are above the user switches in the lower right corner



6.4. User LED's (DS1, DS2, DS3, DS4)

There are four **active low** user LED's, DS1 to DS4, connected directly to 4 MCU ports (PG[2..5]) as shown below. No configuration is required to use the LED's.

Table 6. Use LED's (DS1, DS2, DS3 and DS4)

User LED	MCU Pin
DS1	PG2
DS2	PG3
DS3	PG4
DS4	PG5

6.5. ADC Input Potentiometer (RVAR, RV1)

The ADC Pot is above the hex switch to the left of the GPIO matrix



There is a small variable resistor RV1 on the LCEVB which routes a voltage between 0v and 3.3 V to MCU pin PB4. This is useful for quick ADC testing. Test point RVAR can be used to probe the voltage with a voltmeter.

Note that this circuit provides a very rough way to evaluate the ADC. There is a small current limiting series resistor network to limit the injection current to around 4.4 mA.

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7. MCU Port Pin LCEVB Functions

The table below shows what each MCU pin is used for on the LCEVB.

Table 7. LCEVB 176QFP Port Pin Functions

No	Port A	Port B	Port C	Port D	Port E	Port F	Port G	Port H
0	GPIO	CAN0	JTAG	GPIO ³		GPIO	Ethernet	Ethernet
1	GPIO ²	CAN0	JTAG	GPIO ³		GPIO	Ethernet	Ethernet
2	GPIO ²	LIN0	USB1	GPIO ³	FlexRay A	GPIO	GPIO ^{4,}	Ethernet
3	Ethernet	LIN0	USB1	GPIO ³	FlexRay A	GPIO	GPIO ⁴	
4	GPIO	ADC Pot	FlexRay B	GPIO	FlexRay B	GPIO	GPIO ⁴	
5	GPIO	GPIO	FlexRay A	GPIO	FlexRay B	GPIO	GPIO ⁴	
6	GPIO	GPIO	LIN1	GPIO		GPIO	GPIO	
7	Ethernet	GPIO	LIN1	GPIO		GPIO	GPIO	
8	Ethernet	EXTAL32	RS232	GPIO		GPIO		
9	Ethernet	XTAL32	RS232	GPIO		GPIO		JTAG
10	Ethernet	SAI Audio	CAN1	GPIO		GPIO	USB1	JTAG
11	Ethernet	GPIO	CAN1			GPIO	USB1	USB1
12	GPIO	GPIO	FlexRay	GPIO	Ethernet	GPIO	Ethernet	USB1
13	GPIO	GPIO	FlexRay	GPIO	Ethernet	GPIO	Ethernet	
14	GPIO	GPIO	FlexRay	GPIO	USB1	Ethernet	USB1	
15	GPIO	GPIO	FlexRay	GPIO	USB1	Ethernet	USB1	

No	Port I	Port J
0	GPIO	
1	GPIO	
2	GPIO	
3	GPIO	
4	USB1	
5	USB1	
6	GPIO	
7	USB1	
8	GPIO	
9		
10		
11	Ethernet	
12	GPIO	

Key:	
	Pin not bonded out on 176QFP package
	Pin not accessible on LCEVB

GPIO GPIO

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²Shared with user switches

 $^{^{3}\,\}mathrm{Shared}$ with Hex Encoder Switch

 $^{^4\,\}mathrm{Shared}$ with user LED's

8. Appendix

The MPC5748G LCEVB schematics, Rev B are shown below.

MPC5748G Low Cost Evaluation Board (MPC5748G-LCEVB)

Table Of Contents:	
Power - Main input and 3.3V regulator	Sheet 2
Power - MCU Power	Sheet 3
Power - MCU Decoupling	Sheet 4
Reset and JTAG	Sheet 5
Clocks	Sheet 6
MCU GPIO 1	Sheet 7
MCU GPIO 2	Sheet 8
Comms1 - CAN and LIN	Sheet 9
Comms 2 - FTDI RS232 Interface	Sheet 10
Comms 3 - USB Host Interface (device footprints only)	Sheet 11
Comms 4 - Ethernet (MII Mode)	Sheet 12
Comms 5 - FlexRay	Sheet 13
User - Switches, LED's and Potentiometer	Sheet 14
User - GPIO Pin Matrix	Sheet 15

Caution:

These schematics are provided for reference purposes only. As such,NXP does not make any warranty, implied or otherwise, as to the suitability of circuit design or component selection (type or value) used in these schematics for hardware design using the NXP Calypso family of Microprocessors. Customers using any part of these schematics as a basis for hardware design, do so at their own risk and NXP does not assume any liability for such a hardware design.

Notes:

- All components and board processes are to be ROHS compliant
- All small capacitors are 0402 unless otherwise stated
- All resistors are 0603 5% 0.1w unless otherwise stated. All zero ohm links are 0603
- All connectors and headers are denoted Px and are 2.54mm pitch unless otherwise stated
- All jumpers are denoted Jx. Jumpers are 2mm pitch
- 2 Pin jumpers generally have the "source" on pin 1.
- All switches are denoted SWx
- Test point Vias (just through hole pads) are denoted TPVx

Signals (ports) have not been routed via busses as this makes it harder to determine where each signal goes.

User notes are given throughtout the schematics. Specific PCB LAYOUT notes are detailed in ITALICS

Revision Information

Rev	Date	Designer	Comments		
x1	14 Apr 2015	Alasdair Robertson	Start of capture, Working version (256BGA)		
x2	08 May 2015	Alasdair Robertson	Changed to 176 QFP Package and changed periperhal Matrix		
х3	18 May 2015	Alasdair Robertson	Changes required for initial placement		
x4	19 May 2015	Alasdair Robertson	Tidy Up, Replaced some "hard to source" components		
x5	26 May 2015	Alasdair Robertson	Renumber and Back Annoted from Layout		
х6	27 May 2015	Alasdair Robertson	Correction to GND on 3v3 Regulator circuit		
x7	29 May 2015	Alasdair Robertson	Correction to CAN Test points		
x8	31 May 2015	Alasdair Robertson	Few refdes changes after layout tweaks		
x9	01 Jun 2015	Alasdair Robertson	bertson Correction to user LED Refdes after re-number		
x10	01 Jun 2015	Alasdair Robertson	DNP Jumpers. 0 Ohm resistors added accross LIN jumpers		
A	11 Jun 2015	Andrew MacDonald	Prototype Manufacture Release		
AX1	X1 29 Sep 2015 Alasdair Robertson Prodn Build changes (LIN0 default to Slave, LIN1 Master only)				
			PN Changed to MPC5748G-LCEVB		
AX2	26 Oct 2015	Alasdair Robertson	Change to JTAG Pulls to meet latest RM Spec		
AX3	29 Oct 2015	Alasdair Robertson	tson Changed RV1 current limit resistor. SW4 / SW5 refdes swap		
AX4	09 Dec 2015	Alasdair Robertson	Pull DOWN on TCLK to mitigate against STANDBY exit issue.		
AX5	20 Jan 2016	Alasdair Robertson	Updated NXP Logos		
В	12 Feb 2016	Alasdair Robertson	Updated NXP Logos		

3 Different test points used in design:

TPVx - Through Hole Pad small

TPHx - Through Hile Pad Large (for standard 0.1" header).

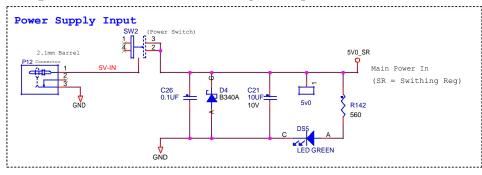
Also used on IO Matrix (IOMx)

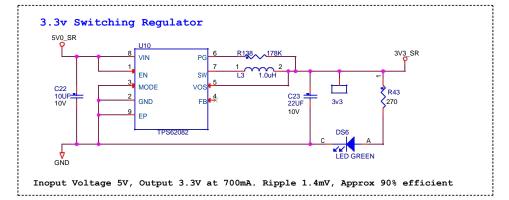
TPX - Surface Mount Wire Loop

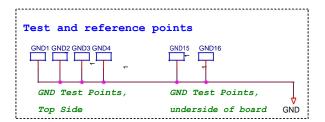


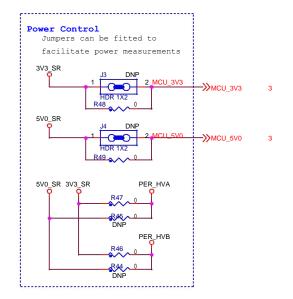
MO			notive Mici (ilbride, Sc	ocontroller Apport	olication	ıs	
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	Date:	Friday, Fe	bruary 12	, 2016	Sheet 1of	15	





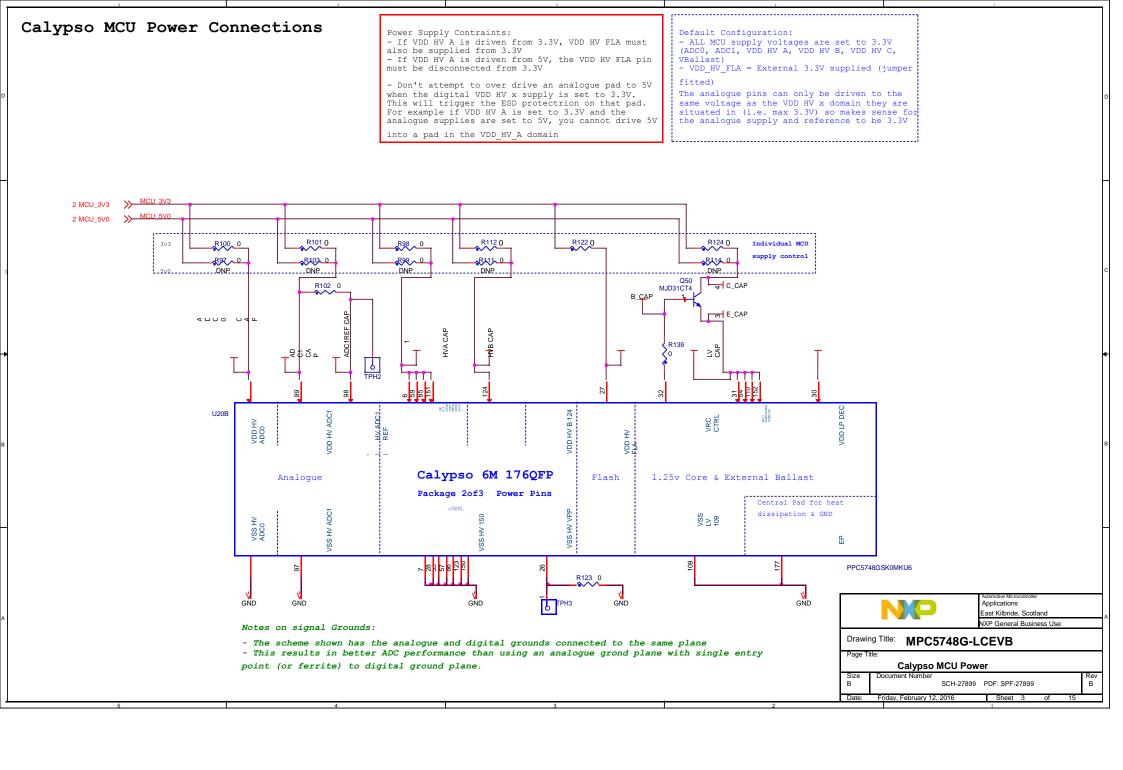




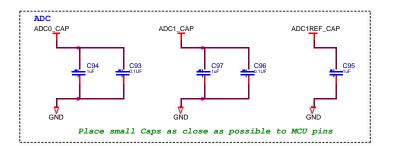


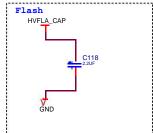


Automotive Microcontroller



Calypso MCU Decoupling and bulk storage



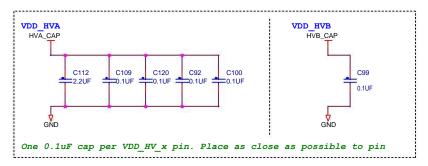


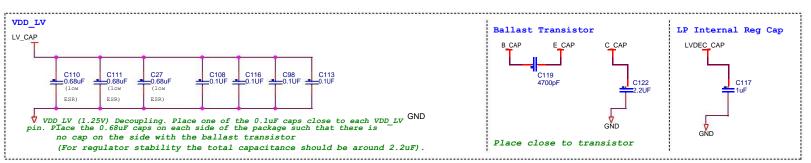
Capacitor Types:

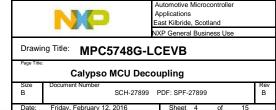
4700pF - Ceramic X7R, 50V 10% 0402
0.1uF - Ceramic X7R, 16V 10% 0402 (Kemet C0402C104K4RAC)

0.68uF - Ceramic X7R, 16V 10% 0805 (Murata GCM219R71C684KA37)
104 0603 Low ESR (Taiyo Yuden LMK107B7105RA-T)

2.2uF - Ceramic X7R, 10V 10% 0603 Low ESR (Taiyo Yuden LMK107B7225KA-TR)



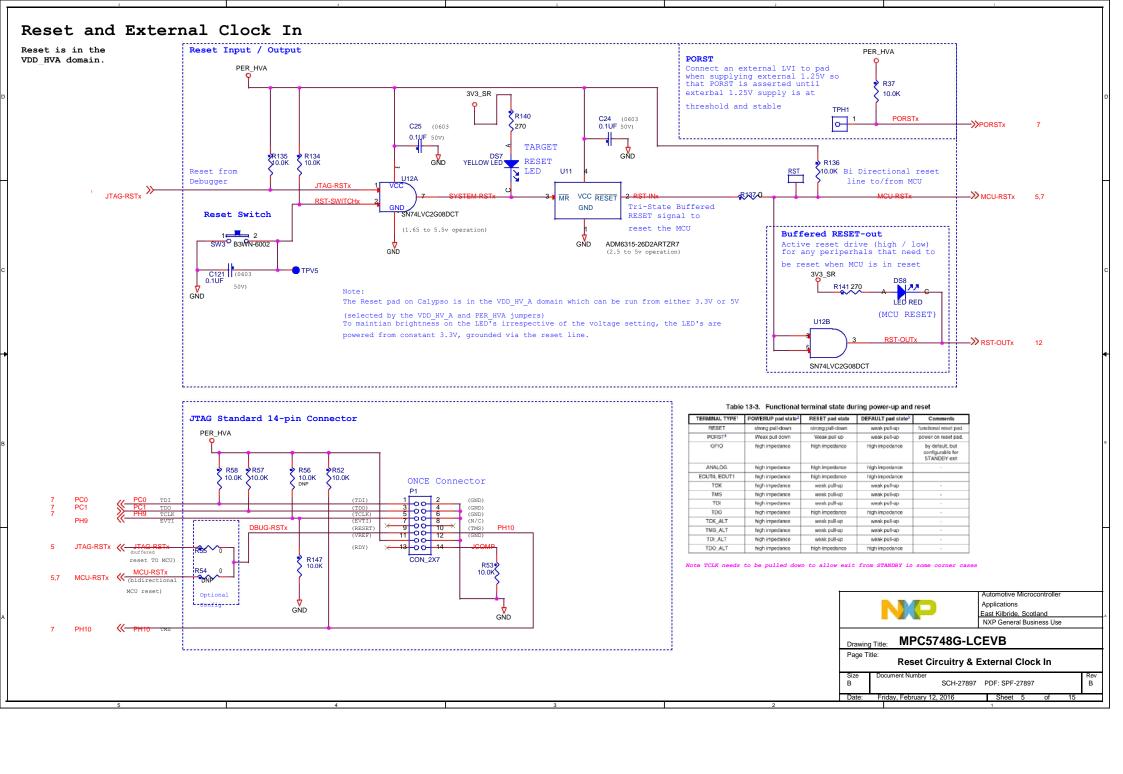


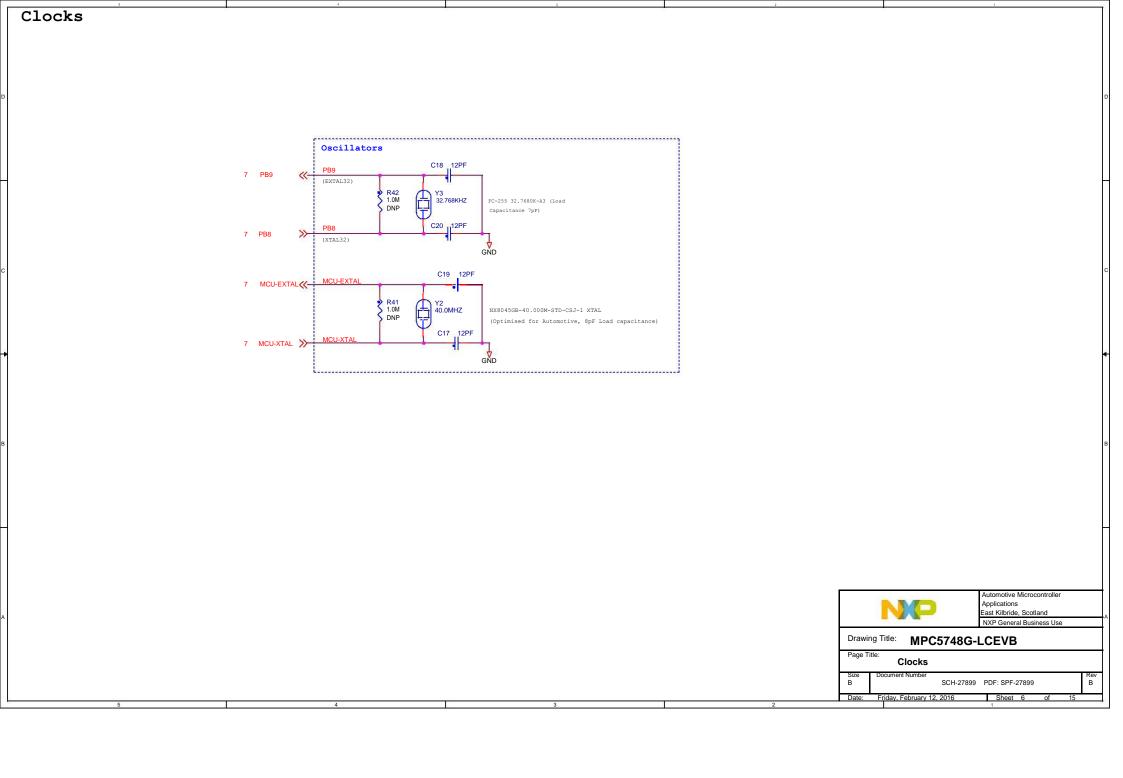


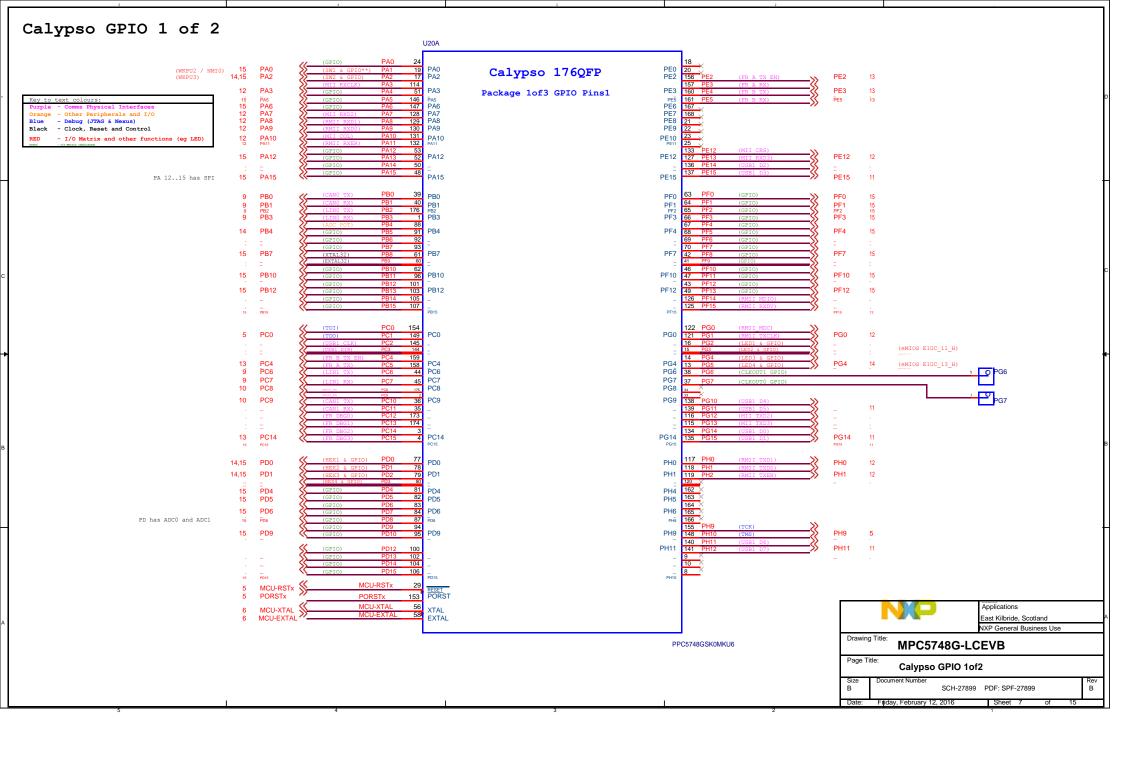
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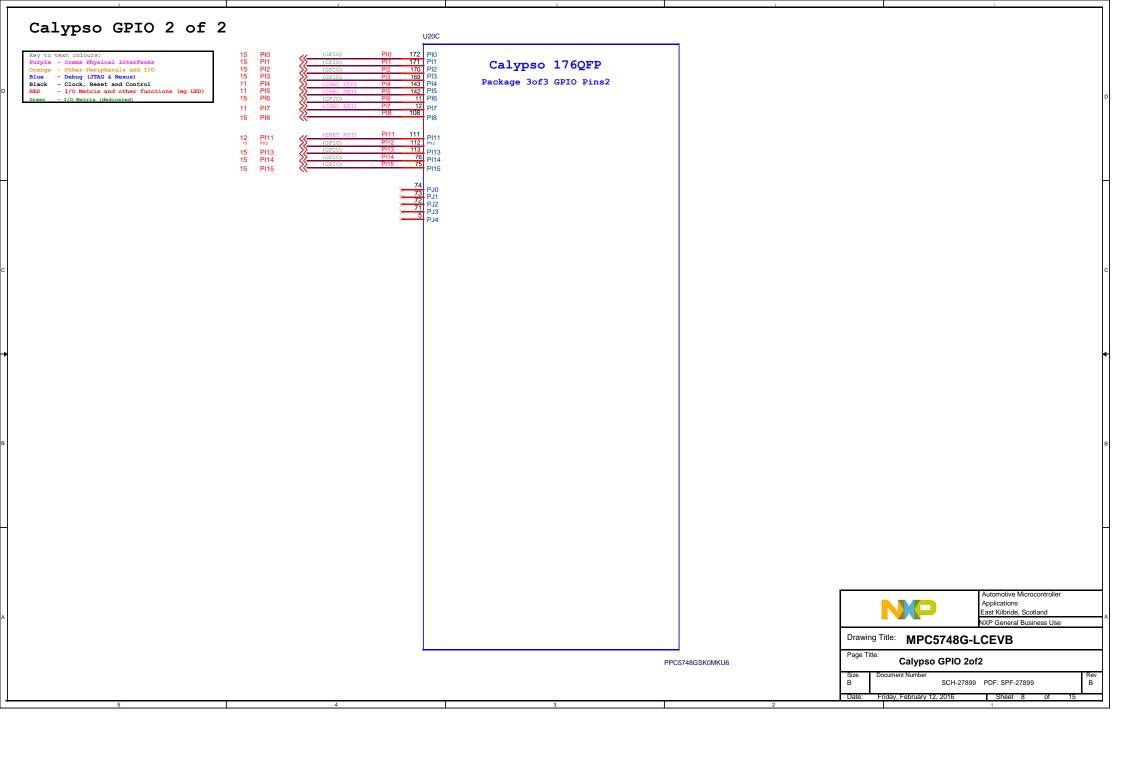
Date: Friday, February 12, 2016 Sheet 4 of 15

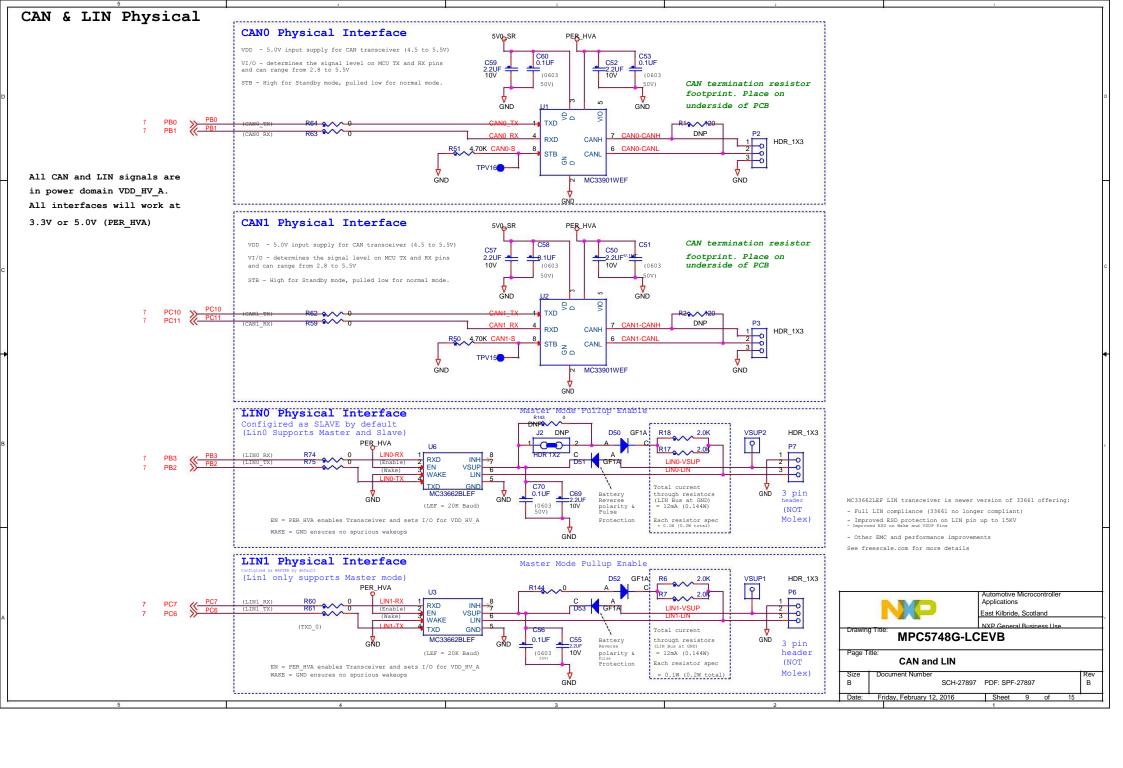
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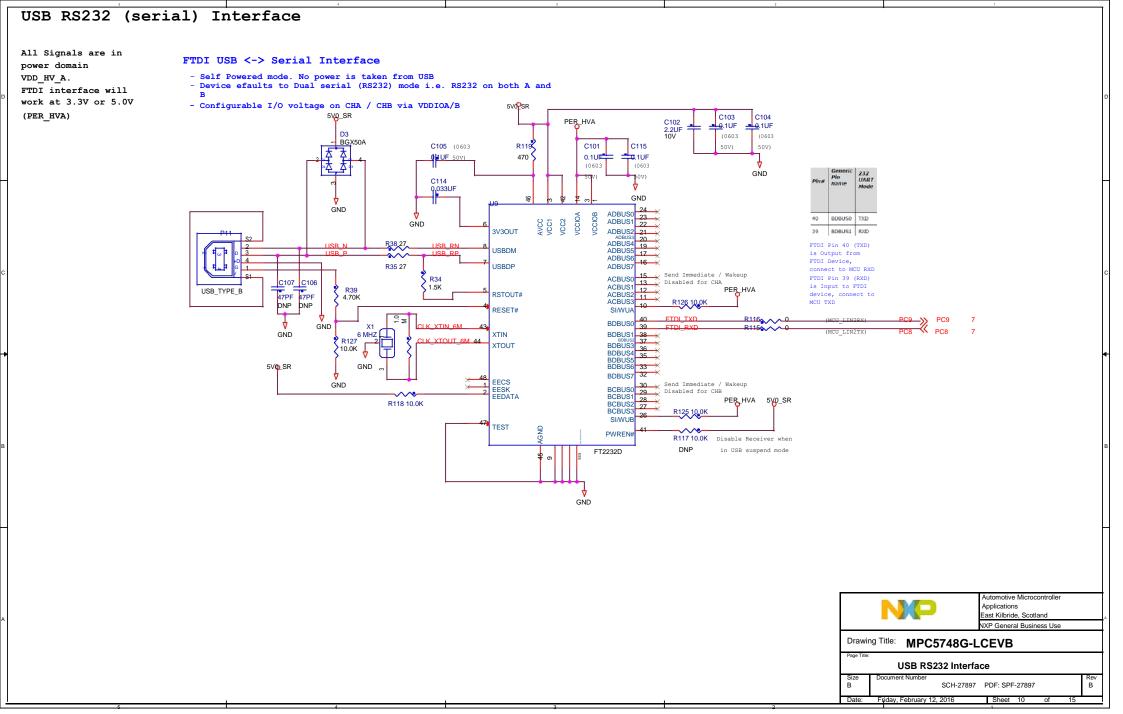


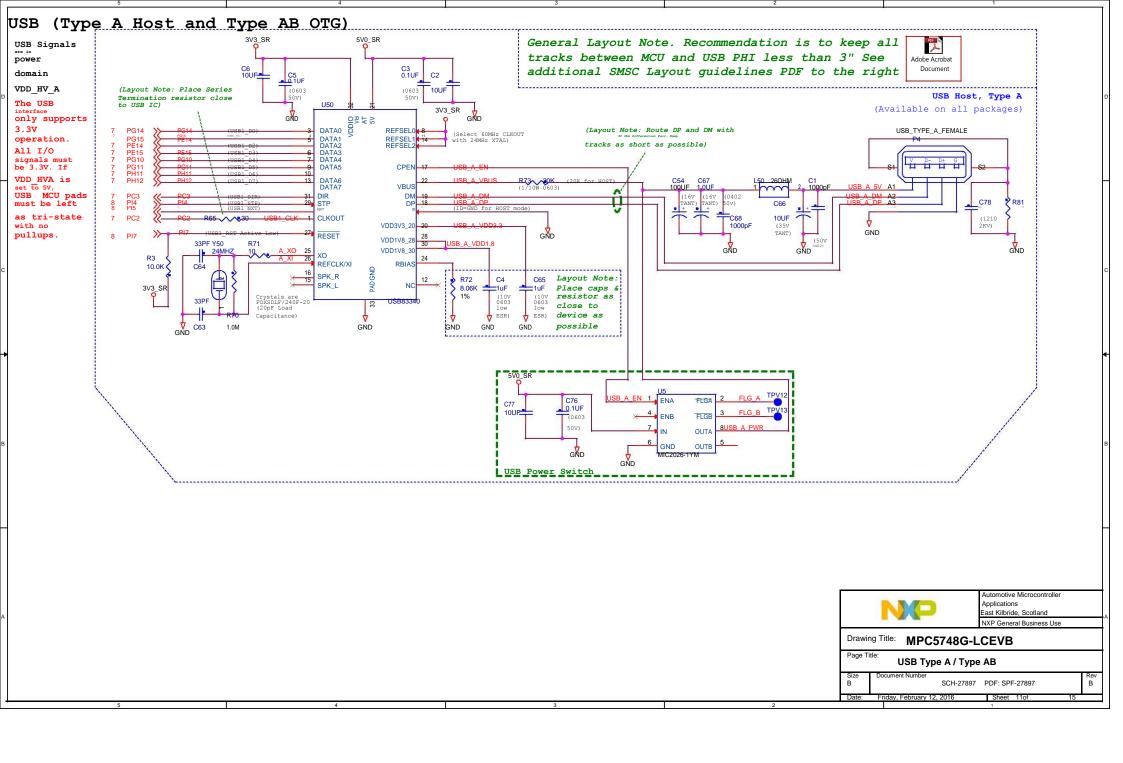


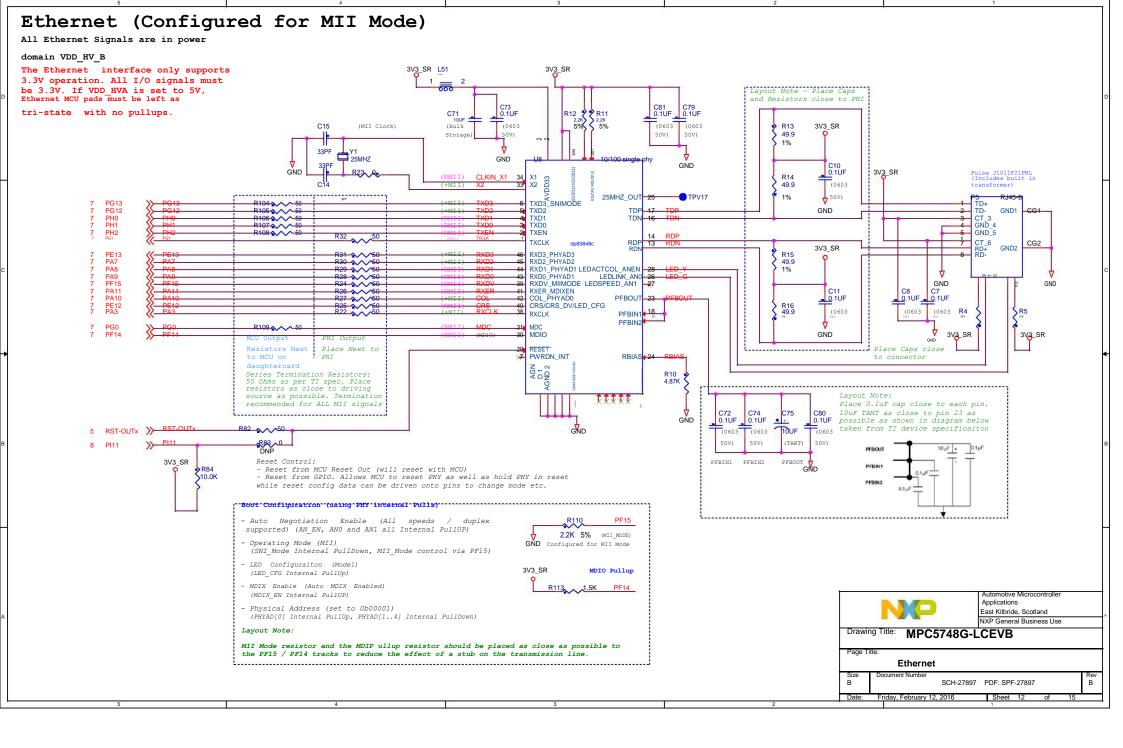


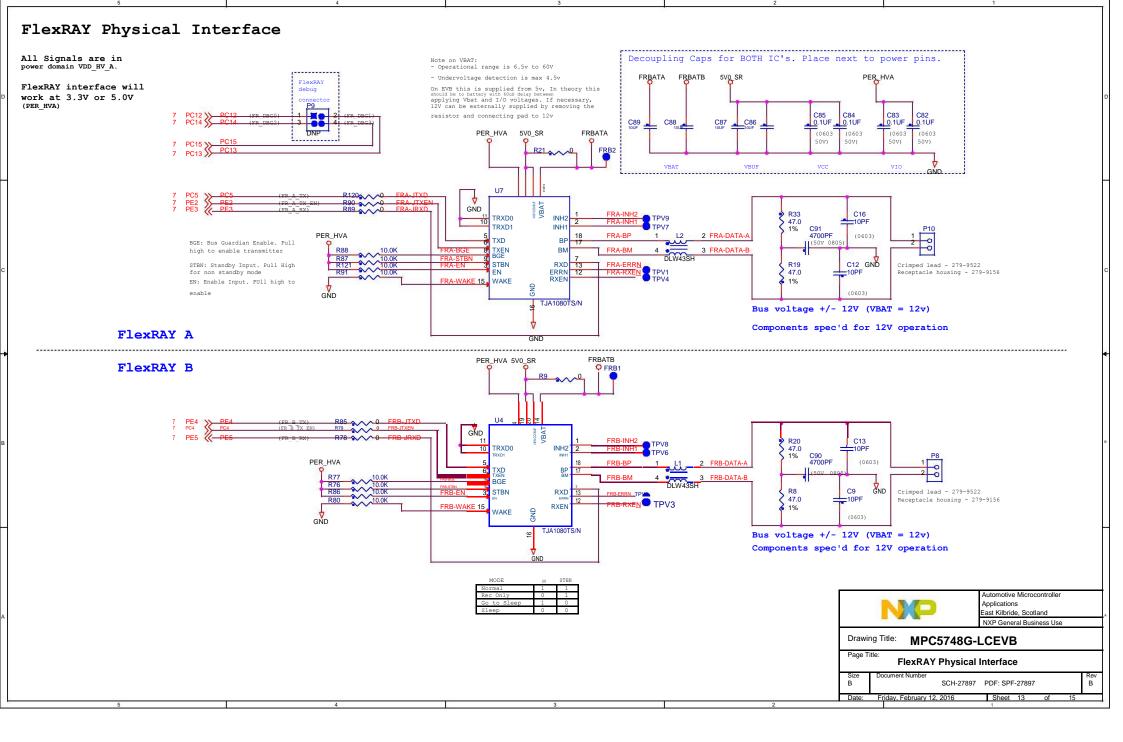


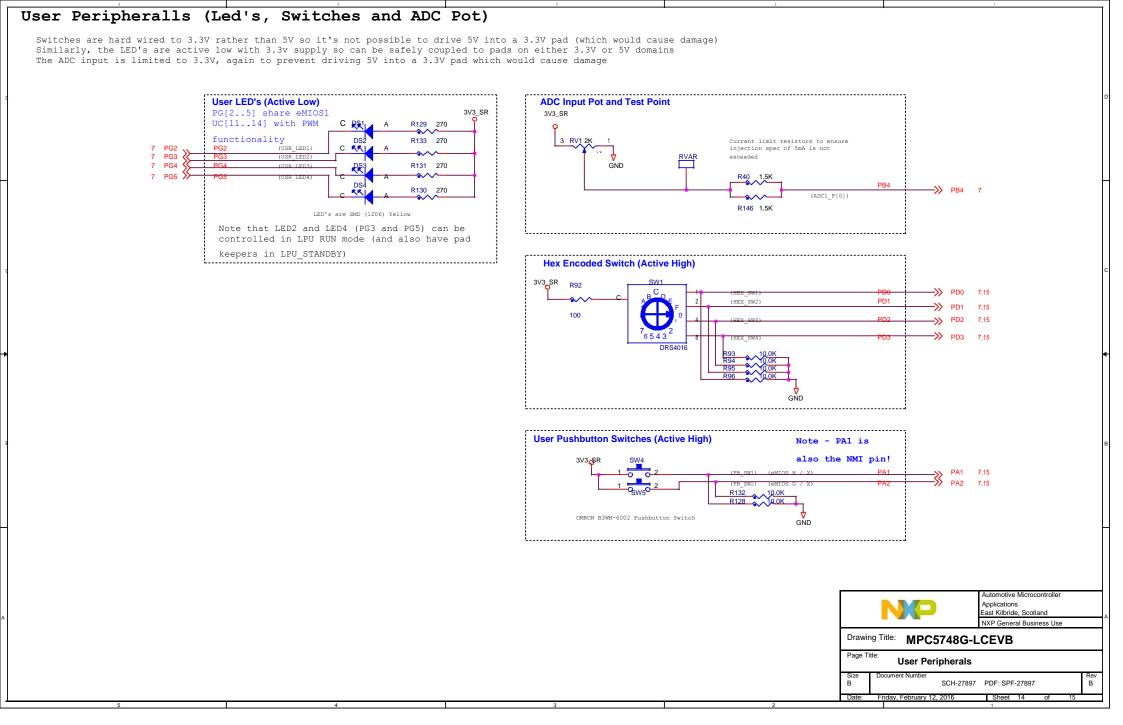


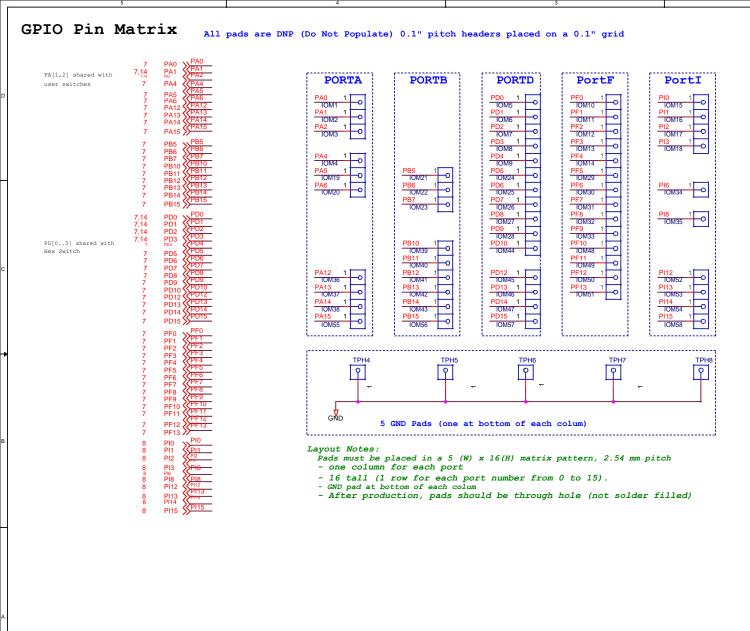














9. Revision History

Date	Substantial changes
March 2016	Initial release
August 2016	Rev. 1: Updated Schematics and Board Pictures

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